

**(a).Statement on Restriction of Hazardous Substances (“RoHS”) for Reedsemi Products**

Reedsemi products are designated as “RoHS Compliant” to comply with EU Directive 2011/65/EU (entered July 21, 2011) and the amended Directive (EU) 2015/863 (effective July 22, 2019) for Restriction of the Use of Hazardous Substances (“RoHS”). To Reedsemi ’s knowledge, Reedsemi products that are declared as RoHS Compliant .

- Do not contain restricted substances above the maximum threshold values shown in Table 1.1  
or
- Where applicable, may be subject to one of the RoHS Annex III exemptions for lead (Pb) as shown in Table 1. 2. (For externally purchased components, other RoHS exemptions may apply):

**Table 1**

<b>Substance</b>	<b>Threshold</b>	<b>EU RoHS Directive</b>
Cadmium (Cd)	0.01% (100ppm)	2002/95/EC amended 2011/65/EU
Lead (Pb)	0.01% (100ppm)	2002/95/EC amended 2011/65/EU
Mercury (Hg)	0.1% (1000ppm)	2002/95/EC amended 2011/65/EU
Hexavalent Chromium (Cr6 )	0.1% (1000ppm)	2002/95/EC amended 2011/65/EU
Polybrominated biphenyls (PBBs)	0.1% (1000ppm)	2002/95/EC amended 2011/65/EU
Polybrominated diphenylethers (PBDEs)	0.1% (1000ppm)	2002/95/EC amended 2011/65/EU
Bis(2-ethylhexyl) phthalate (DEHP)	0.1% (1000ppm)	EU 2015/863, enforced 22 Jul 2019
Butyl benzyl phthalate (BBP)	0.1% (1000ppm)	EU 2015/863, enforced 22 Jul 2019
Dibutyl phthalate (DBP)	0.1% (1000ppm)	EU 2015/863, enforced 22 Jul 2019
Diisobutyl phthalate (DIBP)	0.1% (1000ppm)	EU 2015/863, enforced 22 Jul 2019

**Table 2**

<b>Exemption</b>	<b>Description</b>	<b>Category</b>
7(a)	Lead in high melting temperature type solders (i.e.lead based alloys containing 85 % by weight or more lead)	2002/95/EC amended 2011/65/EU
7(c)-i	Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound	2002/95/EC amended 2011/65/EU
15(a)	Lead in solders to complete a viable electrical connection between the semiconductor die and carrier within integrated circuit flip chip packages where at least one of the following criteria applies: - A semiconductor technology node of 90 nm or larger; - A single die of 300 mm <sup>2</sup> or larger in any semiconductor node; - Stacked die packages with die of 300 mm <sup>2</sup> or larger, or silico interposers of 300 mm <sup>2</sup> or large	2011/65/EU amended (EU) 2019/172: Categories 1 to 7 & 10
15	Lead in solders to complete a viable electrical connection between the semiconductor die and carrier within integrated circuit flip chip packages	2011/65/EU amended (EU) 2019/172: Categories 8, 9 & 11

**(b)Statement on Green product for Reedsemi Products**

"Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

**Halogen-Free**

IEC 61249-2-21 Halogen-Free standard:

Substance	Bromine	Chlorine	Bromine+ Chlorine
ppm	≤ 900	≤ 900	≤ 1500